

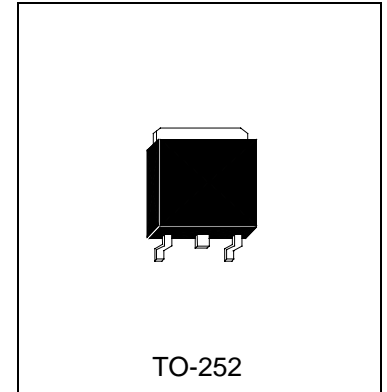


HJ882

NPN EPITAXIAL PLANAR TRANSISTOR

Description

The HJ882 is designed for using in output stage of 20 W audio amplifier, voltage regulator, DC-DC converter and relay driver.



Absolute Maximum Ratings (Ta=25°C)

- Maximum Temperatures
 - Storage Temperature -55 ~ +150 °C
 - Junction Temperature +150 °C
- Maximum Power Dissipation
 - Total Power Dissipation (Tc=25°C)..... 10 W
- Maximum Voltages and Currents
 - BVCBO Collector to Base Voltage 40 V
 - BVCEO Collector to Emitter Voltage 30 V
 - BVEBO Emitter to Base Voltage 5 V
 - IC Collector Current (DC)..... 3 A
 - IC Collector Current (Pulse)..... 7 A
 - IB Base Current (DC)..... 600 mA

Thermal Characteristic

Characteristic	Symbol	Max	Unit
Thermal Resistance, junction to case	Rθjc	12.5	°C/W

Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	40	-	-	V	IC=100uA, IE=0
BVCEO	30	-	-	V	IC=1mA, IB=0
BVEBO	5	-	-	V	IE=10uA, IC=0
ICBO	-	-	1	uA	VCB=30V, IE=0
IEBO	-	-	1	uA	VEB=3V, IC=0
*VCE(sat)	-	0.3	0.5	V	IC=2A, IB=0.2A
*VBE(sat)	-	1	2	V	IC=2A, IB=0.2A
*hFE1	30	-	-		VCE=2V, IC=20mA
*hFE2	160	-	400		VCE=2V, IC=1A
fT	-	90	-	MHz	VCE=5V, IC=0.1A, f=100MHz
Cob	-	45	-	pF	VCB=10V, f=1MHz

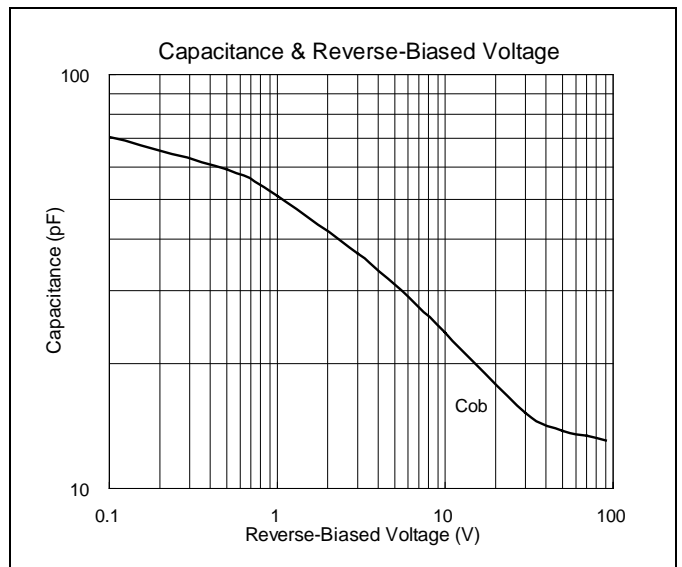
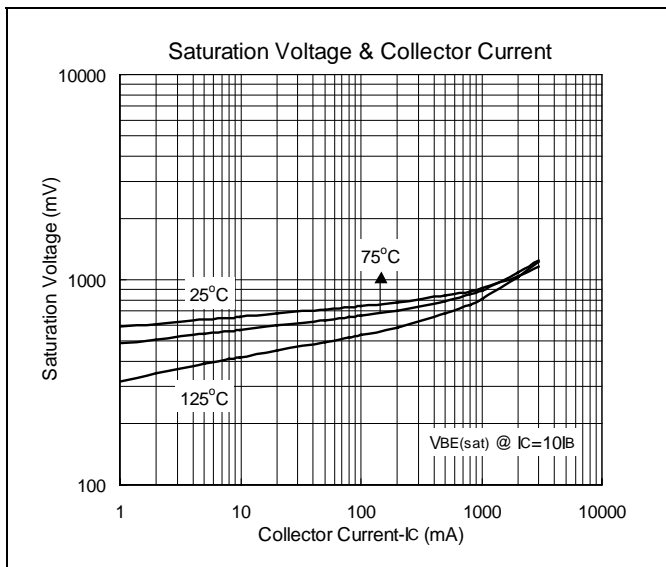
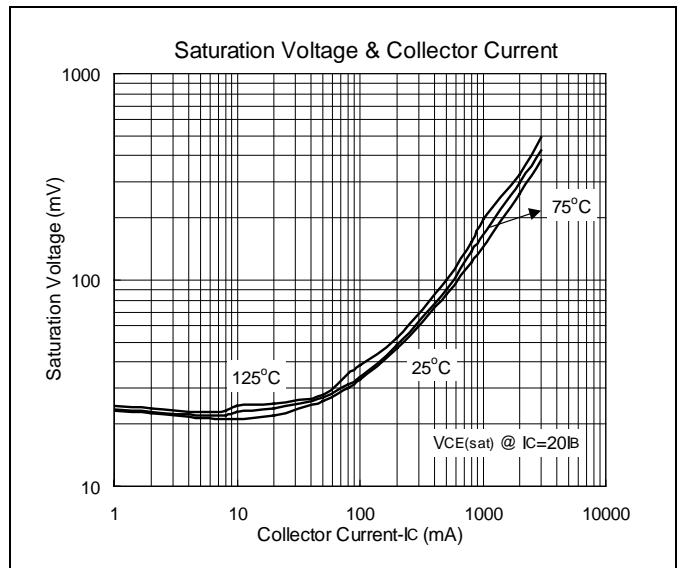
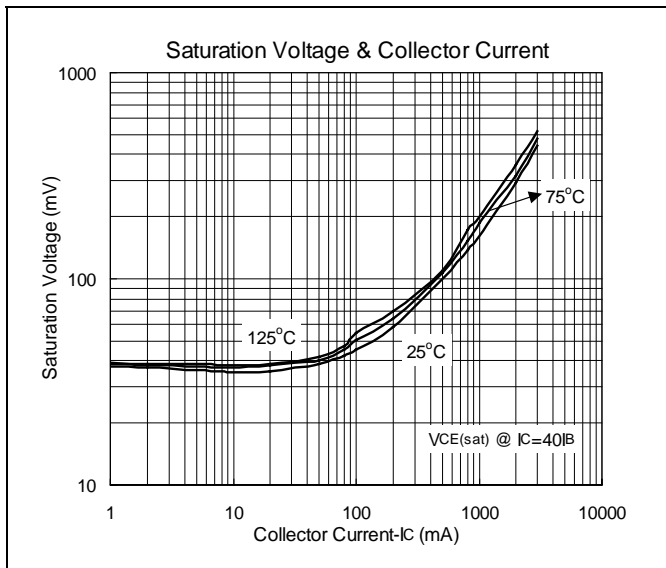
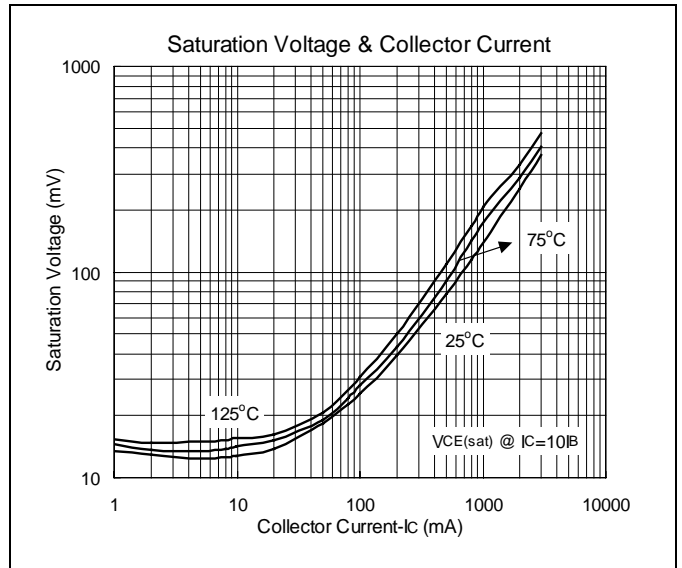
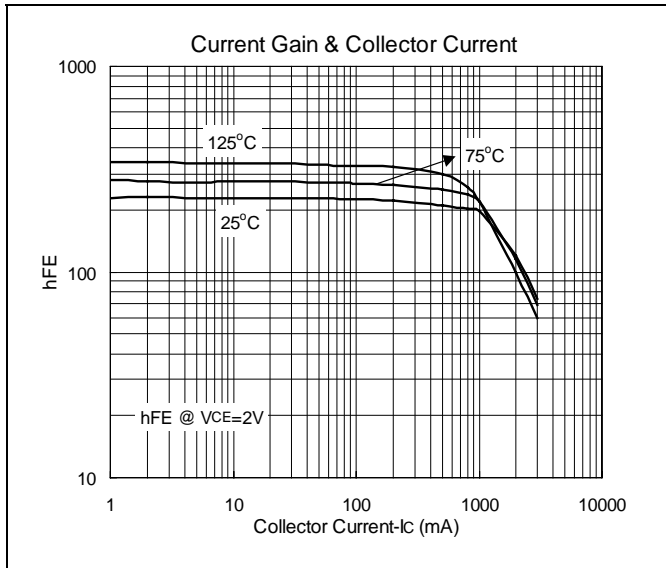
*Pulse Test: Pulse Width ≤380us, Duty Cycle≤2%

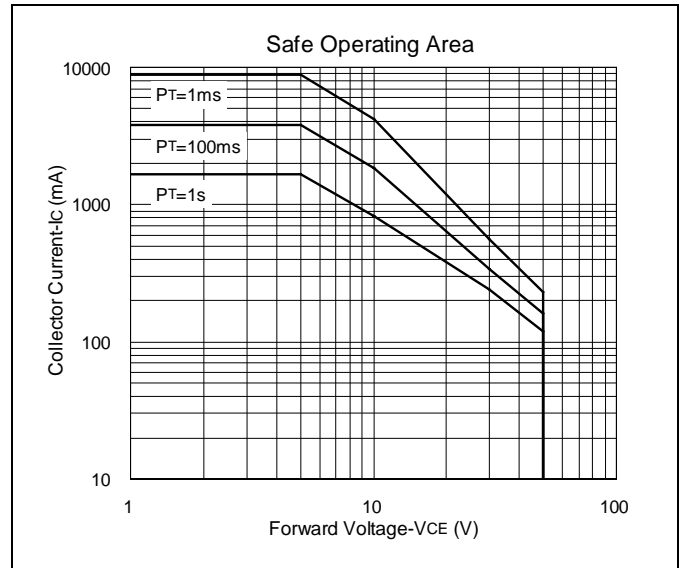
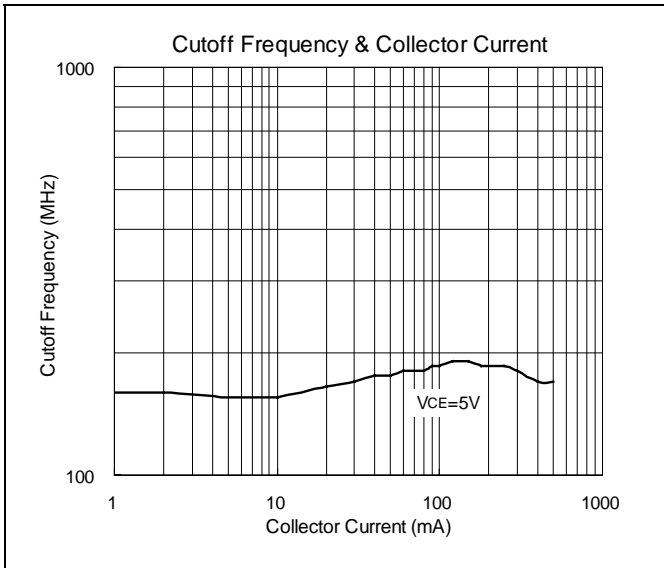
Classification Of hFE1

Rank	Q	P	E
Range	100-200	160-320	250-500



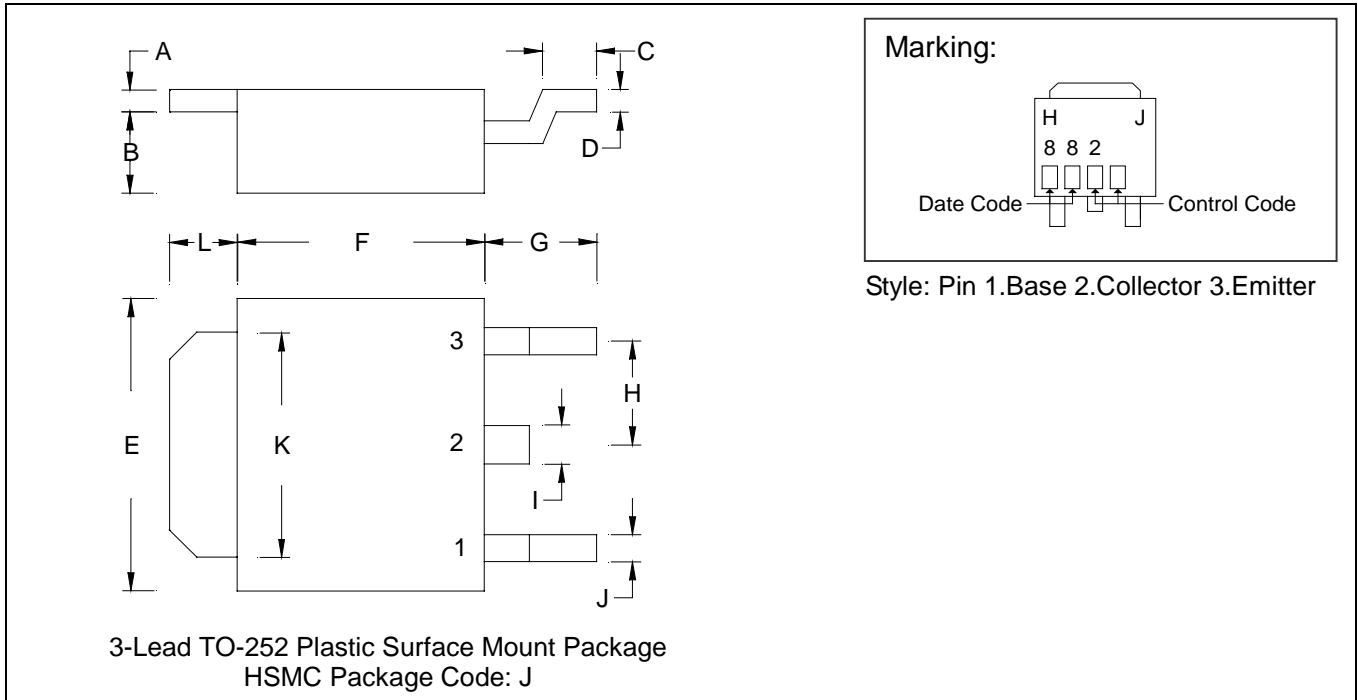
Characteristics Curve







TO-252 Dimension



*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.0177	0.0217	0.45	0.55	G	0.0866	0.1102	2.20	2.80
B	0.0650	0.0768	1.65	1.95	H	-	*0.0906	-	*2.30
C	0.0354	0.0591	0.90	1.50	I	-	0.0354	-	0.90
D	0.0177	0.0236	0.45	0.60	J	-	0.0315	-	0.80
E	0.2520	0.2677	6.40	6.80	K	0.2047	0.2165	5.20	5.50
F	0.2125	0.2283	5.40	5.80	L	0.0551	0.0630	1.40	1.60

- Notes:**
- 1.Dimension and tolerance based on our Spec. dated May. 05,1996.
 - 2.Controlling dimension: millimeters.
 - 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 - 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material:

- Lead: 42 Alloy; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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